2. This document and related artwork are computer generated. Changes are to be performed on the original database on file.

- Solder components using leaded solder, item 3.
- Clean solder flux from board so that there is no discernable residue.
- Mark or inkstam in location shown the dash number, the revision letter, and the serial number "NXXXXX" [where N is a vendor designation letter and XXXX is a unique 5 digit serial number for each part. the vendor designation letter and the starting serial number shall be in accordance with the values provided in the purchase order]. Characters to be 1 mm high minimum.

6. For schematic diagram see JPL drawing 20019308.
7. This printed wiring assembly consists of only surface mount technology.
8. Cross-reference: TMT MICS-400-02300, board connector/coax adapter PCB.

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<th>ITEM NO</th>
<th>REFDES</th>
<th>DAQ</th>
<th>PART OR IDENTIFYING NO</th>
<th>NOMENCLATURE OR DESCRIPTION</th>
<th>SPECIFICATION</th>
<th>MATERIAL OR NOTE</th>
<th>CONTRACT NO</th>
<th>DWN</th>
<th>ENGR</th>
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AR AR 4 6f/3P3937 solder leaded JSTD-035A
AR AR 3 ethene 50-100R catalyst 9 INK, WHITE EPOXY IPC-A-610
1 2 20020113-2 printed wiring board, hall sensor board REV B
1 1 20020113-1 printed wiring board, hall sensor board REV B

Parts list

Jet Propulsion Laboratory
California Institute of Technology
Pasadena, CA 91109

Printed wiring assembly, edge sensor adapter

D. Palmer

Next assembly used on

TMT

See JPL data management system for approval signatures and dates

B 23835

Scale: 21

Sheet 1 of 3
TOP ASSEMBLY (Scale 2:1)

BOTTOM ASSEMBLY (Scale 2:1)

-1 CONFIGURATION
TOP ASSEMBLY (Scale 2:1)

BOTTOM ASSEMBLY (Scale 2:1)

-2 CONFIGURATION